

**CWDM3011P**

**SURFACE MOUNT SILICON  
P-CHANNEL  
ENHANCEMENT-MODE  
MOSFET**


[www.centralsemi.com](http://www.centralsemi.com)
**DESCRIPTION:**

The CENTRAL SEMICONDUCTOR CWDM3011P is a high current silicon P-Channel enhancement-mode MOSFET designed for high speed pulsed amplifier and driver applications. This MOSFET has high current capability with beneficially low  $r_{DS(ON)}$ , and low gate charge.

**SOIC-8 CASE****APPLICATIONS:**

- Load/Power switches
- DC-DC converter circuits
- Power management

**MAXIMUM RATINGS: ( $T_A=25^\circ C$ )**

	<b>SYMBOL</b>		<b>UNITS</b>
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	20	V
Continuous Drain Current (Steady State)	$I_D$	11	A
Maximum Pulsed Drain Current, $t_p=10\mu s$	$I_{DM}$	50	A
Power Dissipation	$P_D$	2.5	W
Operating and Storage Junction Temperature	$T_J, T_{stg}$	-55 to +150	$^\circ C$
Thermal Resistance	$\Theta_{JA}$	50	$^\circ C/W$

**ELECTRICAL CHARACTERISTICS: ( $T_A=25^\circ C$  unless otherwise noted)**

<b>SYMBOL</b>	<b>TEST CONDITIONS</b>	<b>MIN</b>	<b>TYP</b>	<b>MAX</b>	<b>UNITS</b>
$I_{GSSF}, I_{GSSR}$	$V_{GS}=20V, V_{DS}=0$			100	nA
$I_{DSS}$	$V_{DS}=30V, V_{GS}=0$			1.0	$\mu A$
$BV_{DSS}$	$V_{GS}=0, I_D=250\mu A$	30			V
$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	1.4	3.0	V
$V_{SD}$	$V_{GS}=0, I_S=2.6A$			1.3	V
$r_{DS(ON)}$	$V_{GS}=10V, I_D=11A$	12		20	$m\Omega$
$r_{DS(ON)}$	$V_{GS}=4.5V, I_D=8.5A$	15		30	$m\Omega$
$C_{rss}$	$V_{DS}=8.0V, V_{GS}=0, f=1.0MHz$	450			pF
$C_{iss}$	$V_{DS}=8.0V, V_{GS}=0, f=1.0MHz$	3100			pF
$C_{oss}$	$V_{DS}=8.0V, V_{GS}=0, f=1.0MHz$	320			pF
$Q_{g(tot)}$	$V_{DD}=15V, V_{GS}=10V, I_D=11A$	80			nC
$Q_{gs}$	$V_{DD}=15V, V_{GS}=10V, I_D=11A$	7.0			nC
$Q_{gd}$	$V_{DD}=15V, V_{GS}=10V, I_D=11A$	10.1			nC
$t_{on}$	$V_{DD}=15V, V_{GS}=10V, I_D=1.0A$	49			ns
$t_{off}$	$R_G=6.0\Omega, R_L=15\Omega$	330			ns

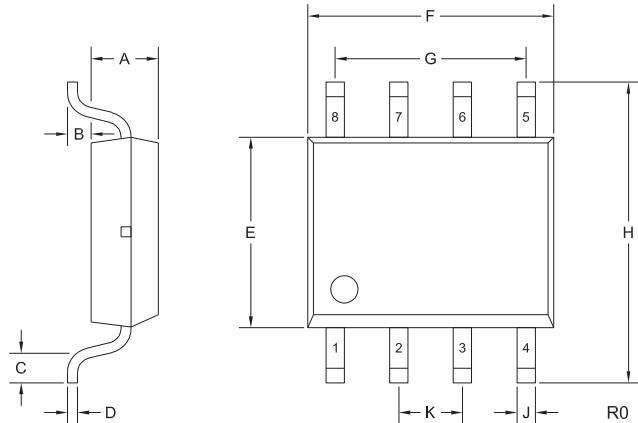
R1 (6-August 2013)

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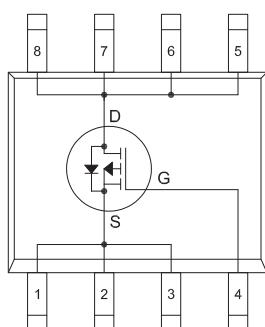
### SOIC-8 CASE - MECHANICAL OUTLINE



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.049	0.057	1.24	1.44
B	0.000	0.011	0.00	0.27
C	0.018	-	0.46	-
D	0.006	0.011	0.16	0.27
E	0.145	0.154	3.70	3.90
F	0.189	0.198	4.81	5.01
G	0.150		3.81	
H	0.231	0.244	5.88	6.18
J	0.013	0.021	0.35	0.52
K	0.050		1.27	

SOIC-8 (REV: R0)

### PIN CONFIGURATION



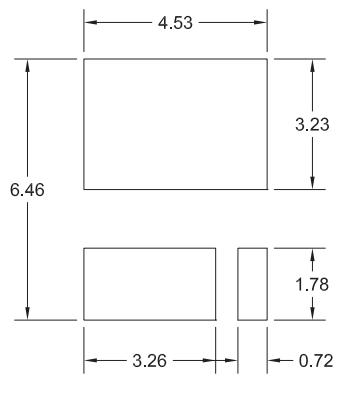
### LEAD CODE:

- |           |          |
|-----------|----------|
| 1) Source | 5) Drain |
| 2) Source | 6) Drain |
| 3) Source | 7) Drain |
| 4) Gate   | 8) Drain |

**MARKING CODE: C3011P**

### SUGGESTED MOUNTING PADS

(Dimensions in mm)



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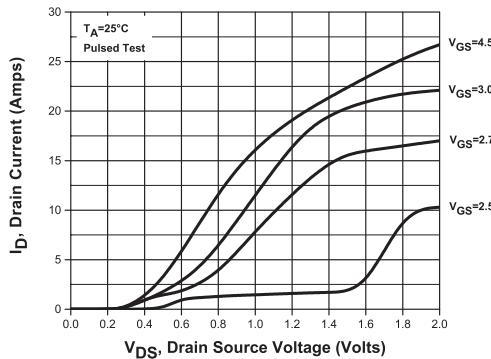
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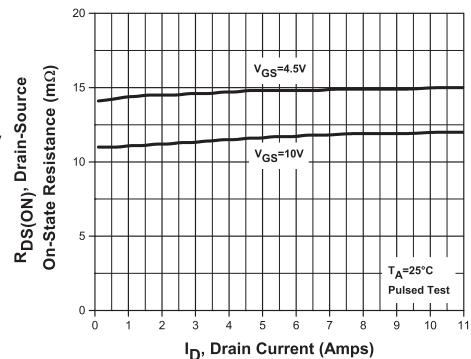


**TYPICAL ELECTRICAL CHARACTERISTICS**

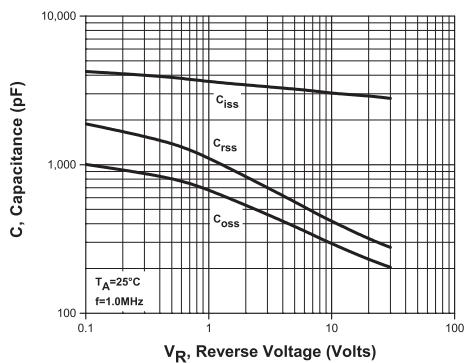
**Output Characteristics**



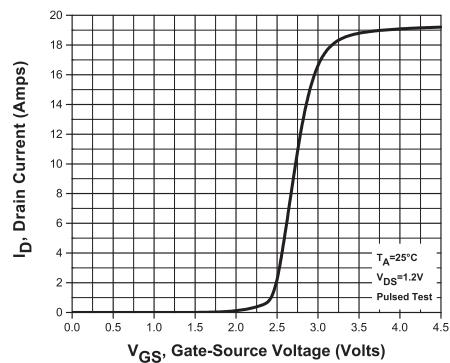
**Drain Source On Resistance**



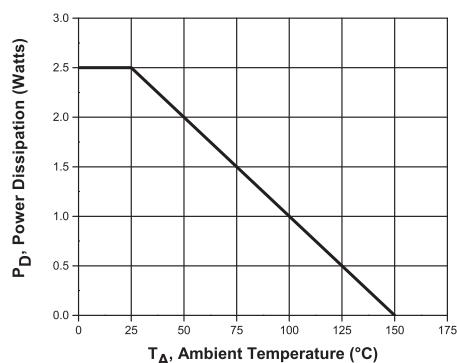
**Capacitance**



**Transfer Characteristics**



**Power Derating**



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